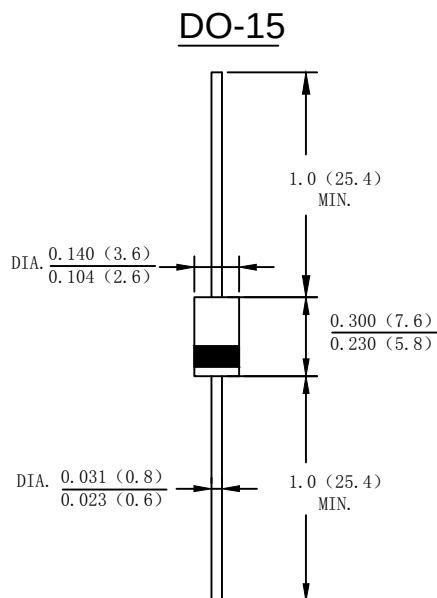


Features

- Ultrafast 50 Nanosecond Recovery Times
- 150°C Operating Junction Temperature
- Low Forward Voltage
- Low Leakage Current
- High Temperature Glass Passivated Junction
- High temperature soldering : 260°C / 10 seconds at terminals

Mechanical Data

- Case: Molded plastic DO-15
- Terminals: Plated leads solderable per MIL-STD-202, Method 208 guaranteed
- Polarity: Color band denotes cathode end
- Mounting Position: Any
- Marking: Type Number
- Lead Free: For RoHS/Lead Free Version



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load

For capacitive load derate current by 20%

Type Number	SYMBOL	MUR240G	Unit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	400	V
Maximum RMS Voltage	V_{RMS}	280	V
Maximum DC Blocking Voltage	V_{DC}	400	V
Average Rectified Output Current (Note 1) @ $T_A = 85^\circ\text{C}$	I_O	2.0	A
Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	60	A
Forward Voltage @ $I_F = 2.0\text{A}$, $T_A = 25^\circ\text{C}$	V_{FM}	1.3	V
Peak Reverse Current @ $T_A = 25^\circ\text{C}$	I_R	5.0	μA
At Rated DC Blocking Voltage @ $T_A = 100^\circ\text{C}$		100	
Maximum Reverse Recovery Time (Note 2)	T_{RR}	50	nS
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$	50	$^\circ\text{C/W}$
Operating Temperature Range	T_J	-55 to + 150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to + 150	$^\circ\text{C}$

Note: 1. Leads maintained at ambient temperature at a distance of 9.5mm from the case

2. Reverse Recovery Test Conditions: $I_F = 0.5\text{A}$, $I_R = 1\text{A}$, $I_{rr} = 0.25\text{A}$.

FIG. 1 – FORWARD CURRENT DERATING CURVE

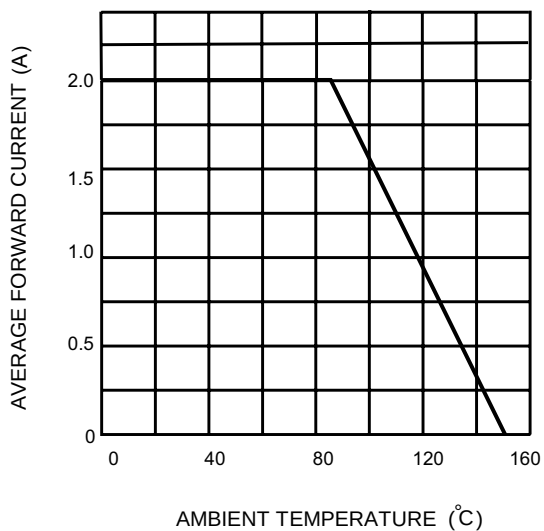


FIG.2-TYPICAL FORWARD CHARACTERISTICS

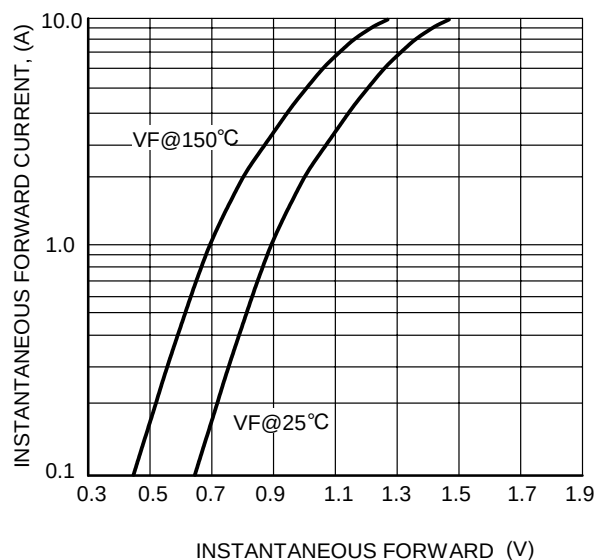


FIG. 3 – MAXIMUM NON-REPEITITIVE SURGE CURRENT

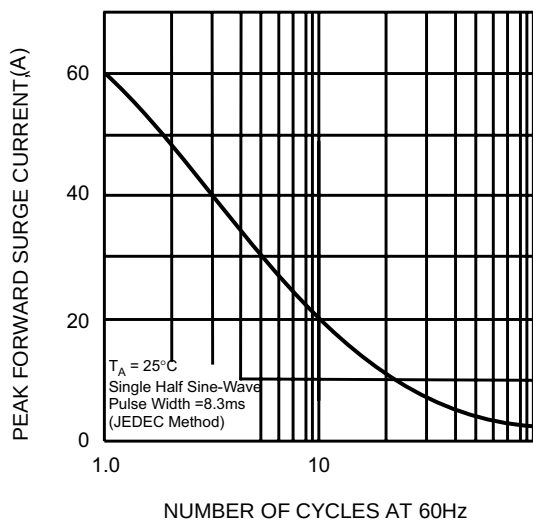


FIG.4 – TYPICAL JUNCTION CAPACITANCE

